

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

What is claimed is:

Claim 1 (currently amended). A light emitting device package, comprising:
a semiconductor junction operable to emit light when biased;
an homogenous composition deposited on the semiconductor junction adapted to filter and combine predetermined wavelengths of light from the semiconductor surface; ;
the homogenous composition further comprising a pressed and sintered mixture of a molding compound and a powdered luminous substance;

Claim 2 (canceled).

Claim 3 (canceled).

Claim 4 (currently amended). The light emitting device package of Claim 3 1, the ~~pelletized~~ molding compound further comprising a clear epoxy.

Claim 5 (canceled).

Claim 6 (currently amended). The light emitting device package of Claim 5 1, wherein the luminous powder is less than or equal to 5 microns in size, ~~prior to sintering and pelletization.~~

Claim 7 (currently amended). The light emitting device package of Claim 6 1, wherein the luminous powder is spherical or flake-like in shape, ~~prior to sintering and pelletization.~~

Claim 8 (currently amended). The light emitting device package of Claim 2 1, the molding compound further comprising a clear epoxy.

Claim 9 (canceled).

Claim 10 (currently amended). The light emitting device package of Claim 2 1, the luminous substance further comprising a Cerium doped garnet.

Claim 11 (currently amended). The light emitting device package of Claim 2 1, the luminous substance further comprising YAG:Ce.

Claim 12 (canceled).

Claim 13 (canceled).

Claim 14 (canceled).

Claim 15 (canceled).

Claim 16 (withdrawn). A method of fabricating a light emitting device, comprising:

admixing a luminous substance to a transferable grade molding compound to derive a homogeneous mixture;

pressing and sintering the homogeneous mixture into solid pellets;

processing the solid pellets for application on a semiconductor surface; and

depositing the processed solid pellets on the semiconductor surface.

Claim 17 (withdrawn). The method of fabricating a light emitting device of Claim 16 wherein the molding compound is in a pelletized form prior to pressing and sintering the homogeneous mixture into solid pellets.

Claim 18 (withdrawn). The method of fabricating a light emitting device of Claim 16 wherein the pelletized molding compound further comprises a clear epoxy.

Claim 19 (withdrawn). The method of fabricating a light emitting device of Claim 16 wherein the molding compound is in a powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

Claim 20 (withdrawn). The method of fabricating a light emitting device of Claim 19 wherein the powdered molding compound further comprises a clear epoxy.

Claim 21 (withdrawn). The method of fabricating a light emitting device of Claim 16 wherein the luminous substance is in powdered form prior to pressing and sintering the homogeneous mixture into solid pellets.

Claim 22 (withdrawn). The method of fabricating a light emitting device of Claim 16 wherein the light emitted by the light emitting device comprises a white light.

Claim 23 (withdrawn). A method of fabricating a light emitting chip comprising depositing an admixed substance of epoxy and a luminous substance around an LED chip located on a copper lead frame.